



Product Content Sheet

Package family	QLPp	Picture of typical product, optional
Date	28/Sep/2006	
Version	RoHS	

Composition part	Material group	Materials	CAS if applicable	Average mass [weight-% *)	Sum [%]	Traces
Chip	Silicon and inorganic compounds	Si	7440-21-3	100	0.940999	-
Wires	Nobel Metal	Gold	7440-57-5	99.99	0.139895	-
Leadframe	Alloy	Copper	7440-50-8	96.6602	49.625027	-
		Iron	7439-89-6	2.1697	1.113917	-
		Phosphorus	7723-14-0	0.0724	0.037170	-
		Zinc	7440-66-6	0.1116	0.057295	-
		Lead	7439-92-1	0.0129	0.006623	-
		Silver	7440-22-4	0.9732	0.499638	-
Mold compound	Silica and thermoset epoxy resin	Si fused	60676-86-0	86.91	37.506977	-
		Epoxy & Phenol resin	Confidential	12.78	5.515351	-
		Carbon Black	1333-86-4	0.31	0.133784	-
DA Epoxy	Epoxy	Silver	7440-22-4	75	0.884539	-
		Epoxy Resin	Confidential	10	0.117939	-
		Gamma Butyrolactone	96-48-0	5	0.058969	-
		Amine	Confidential	5	0.058969	-
		Metal Oxide	Confidential	5	0.058969	-
Leadfinish	Metal Alloy	Sn	7440-31-5	100	3.243938	-
Marking	Laser	Laser	-	-	-	-
Sum in total:					100	-

Weight range	0.159405g
Fluctuation margin	-

or:

Case sizes**) and weight range

-

*) related to package weight; weight in particular, see corresponding *package weight list*

**) optional

Not part of package family	
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Company	Texas Instruments Norway	Important remarks: 1) Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight. Higher limits are accepted if the substance or material is legally regulated (see note no. 2). 2) A list of the (legal) "... restrictions on substances ..." or materials is available at internet address: http://www.eicta.org/Content/Default.asp?PageID=113 .
Address	Gaustadalleen 21, 0349 Oslo, Norway	
Support	http://www-k.ext.ti.com/sc/technical-support/pic/euro.htm	
Internet	www.ti.com	

- 3) Substances, materials etc. with possible harmful effects on human beings and the environment are listed.
- 4) There are no risks for human beings and to the environment if products are properly used as designated.
This shall not apply to risks caused during procedures for disposal etc.
- 5) All statements herein are based on our present knowledge. If our products are used properly, there are no risks to human beings and/or the environment.



Package Weight List

(Single weights of Products, materials data see Product Content Sheet on previous page)

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Uspec short*)	Package family*)	Package	Internal package code	Pin count	Weight [grams]	Remark
		4x4x0.85 QLPp	QLPp 16	16	0.159405 g	Device: CC2550

*) USpec short name and Package family are optional, e.g. for summary of several package weight lists

Company	Texas Instruments Norway
Address	Gaustadalleen 21, 0349 Oslo, Norway
Support	http://www-k.ext.ti.com/sc/technical-support/pic/euro.htm
Internet	www.ti.com

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